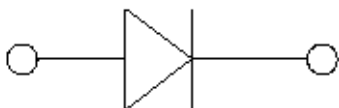


Small-Signal Fast Switching Diodes



Features

- V_R 100V
- I_{FAV} 200mA

Typical Applications

- Low-Leakage

Mechanical Data

- **Package:** SOD323
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end
- **Marking:** D4

■Maximum Ratings ($T_A=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE
Repetitive peak reverse voltage	V_{RRM}	V		85
Reverse voltage	V_R	V		100
Peak forward surge current	I_{FSM}	A	Non-Repetitive $t = 1 \mu\text{s}$	4
Average forward current	I_{FAV}	mA		200
Power dissipation	P_{tot}	mW		250
Thermal Resistance Junction to Ambient Air	$R_{\theta JA}$	$^\circ\text{C}/\text{W}$		500
Maximum junction temperature	T_j	$^\circ\text{C}$		150
Storage temperature range	T_{stg}	$^\circ\text{C}$		-55 to +150

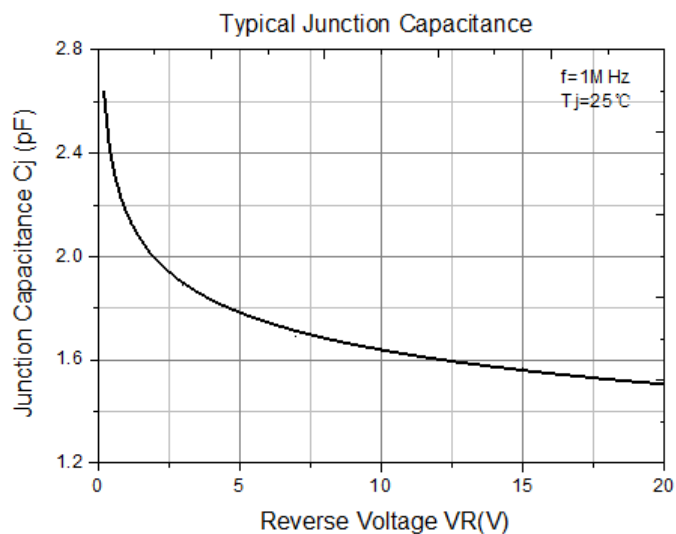
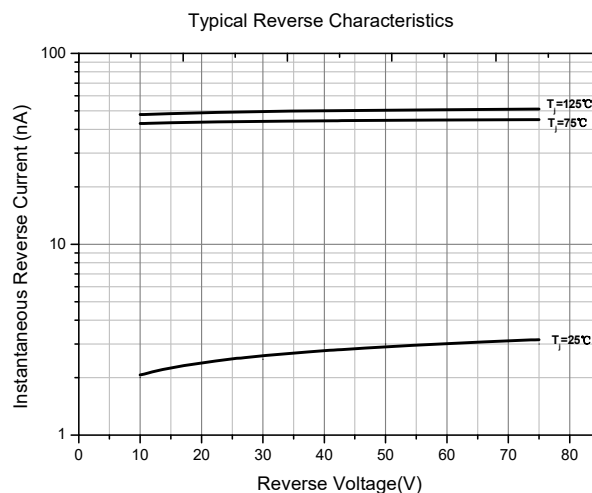
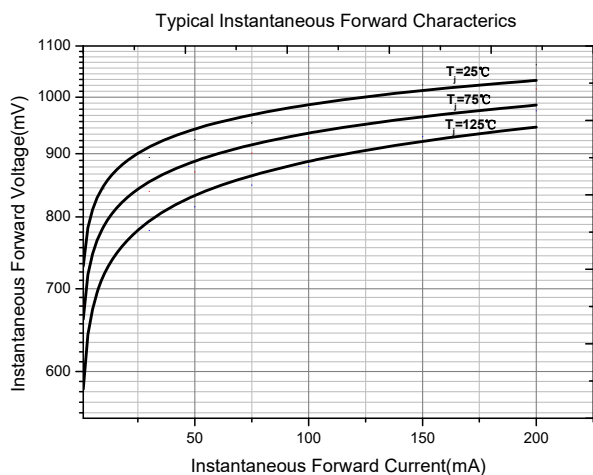
■Electrical Characteristics ($T_A=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER	Symbol	UNIT	Conditions	Min	Max
Breakdown Voltage	V_R	V	$I_R=100\mu\text{A}$	100	
Forward Voltage	V_F	V	$I_F=1\text{mA}$		0.9
			$I_F=10\text{mA}$		1.0
			$I_F=50\text{mA}$		1.1
			$I_F=150\text{mA}$		1.25
Reverse Leakage Current	I_R	nA	$V_R=75\text{V}$		5
Capacitance	C	pF	$V_R=0\text{V}, f=1\text{MHz}$		4
Reverse Recovery Time	T_{rr}	us	$I_F=I_R=10\text{mA}, I_{rr}=0.1 \cdot I_R, R_L=100\Omega$		3

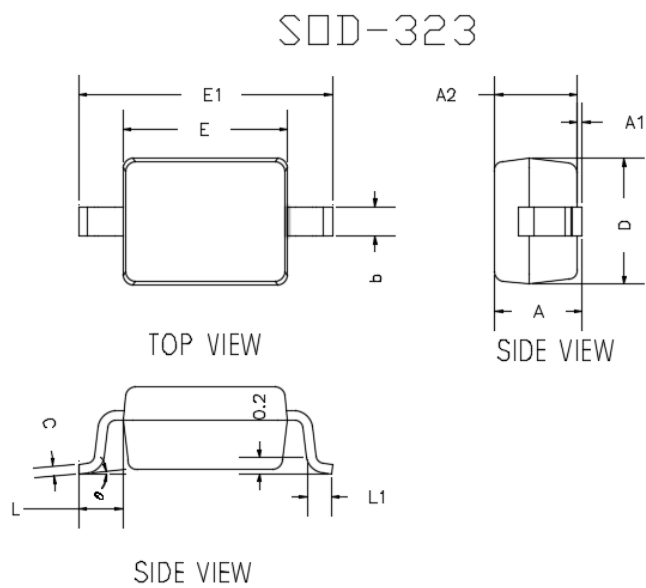
■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
BAS416	F2	Approximate 0.0048	3000	30000	120000	7" reel

■ Characteristics (Typical)

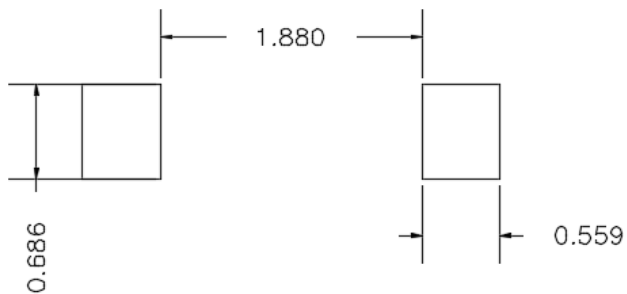


■Outline Dimensions



DIMENSIONS				
DIM	INCHES		MM	
	MIN	MAX	MIN	MAX
A	---	0.0393	---	1.0000
A1	0.0000	0.0039	0.0000	0.1000
A2	0.0314	0.0354	0.8000	0.9000
b	0.0098	0.0157	0.2500	0.4000
c	0.0031	0.0059	0.0800	0.1500
D	0.0472	0.0551	1.2000	1.4000
E	0.0629	0.0709	1.6000	1.8000
E1	0.0984	0.1063	2.5000	2.7000
L	0.0187TYP		0.475TYP	
L1	0.0098	0.0157	0.250	0.400
θ	0°	8°	0°	8°

■Soldering Footprint



UNIT: mm

SUGGESTED SOLDER PAD LAYOUT

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